First ideas on serial powering for the ePIC SVT

L. Gonella (Birmingham), P. Phillips (RAL), I. Sedgwick (RAL), F. Wilson (RAL) EIC SC general meeting 30 January 2023

Outline

- Serial powering basics
- Example: ATLAS ITk pixel detector
- Possible implementation for ePIC SVT

Serial powering basics

- Serial powering is a current based powering scheme, where modules are powered in series by a constant current.
 - The current to voltage conversion is done by regulators on module.
- In a serial powering chain made of n modules, the transmitted current is only the current needed by one module, I.
- For n modules powered in series, the current is reduced of a factor n with respect to a direct powering scheme → Higher power efficiency and reduced cable volume.
 - Cable cross-section and the power losses on the cables scale by the same factor.



Serial powering basics

- As the modules are powered with a constant current, V_{drop} is not constrained as in a voltage based powering scheme.
 - It can in principle be chosen only depending on the output voltage capability of the current source and of the allowed power density (i.e. cooling capability).
- Higher V_{drop} can be allowed in the active area of the detector to reduce the material budget of the cables.
 - Outside the detector the voltage drop can be reduced to lower the power losses.
- With respect to voltage based powering schemes (incl. DC-DC), serial powering allows more flexibility in the optimization of material and power efficiency.



Mod 1

Rnl²

Direct powering

Mod 2

nV

Regulator

Mod 2

Regulator

Mod 1

Mod n

Serial powering

Serial powering basics

- The voltage across the chain is nV, where V is the voltage on a module.
- Each module sits at a different ground potential.
- AC coupled data transmission required.
 - DC balanced data protocol (e.g. 8b10b).
 - Self biased receiver inputs to set the common mode voltage.





Example: ATLAS ITk detector

- The ATLAS pixel detector at the HL-LHC adopted serial powering (also the CMS pixel detector).
- Each module is made of a sensor bump bonded to a certain number of readout chips.
 - In the sketch, four readout chip per module (FE).
- The current flows in series between modules and in parallel between readout chips on a module.
- In each chip, two shunt-LDO regulators generate the analogue (V_{DDA}) and digital (V_{DDD}) voltages.



The shunt-LDO regulator

- For this powering scheme, on-chip regulators are needed that can:
 - Operate in parallel;
 - Generate different output voltages out of the current supply;
 - Shunt additional current in case of device failure.
- The Shunt-LDO regulator was designed to match these requirements.
 - First version in the ATLAS pixel FEI4 chip (180 nm process).
 - Full SP version in the RD53 chip (65 nm process).
- · It combines two regulation loops.
 - Shunt regulation circuitry → regulates the current to the chip.
 - LDO (Low Drop Out) regulation loop → generates the voltage for the chip.



Some references on ATLAS SP & Shunt-LDO

- L. Gonella, PhD thesis, <u>https://cds.cern.ch/record/1633150?ln=en</u>
- L. Gonella, D. Arutinov, M. Barbero et al. 'A serial powering scheme for the ATLAS pixel detector at sLHC'. In: JINST 5 (2010), p. C12002. doi: 10.1088/1748-0221/5/ 12/C12002.
- M. Karagounis, D. Arutinov, M. Barbero et al. 'An Integrated Shunt-LDO Regulator for Serial Powered Systems'. In: Proc. of the European Solid-State Device Conference, ESSCIRC 2009 (2009), pp. 276-279. doi: 10.1109/ESSCIRC.2009.5325974.
- L. Gonella, M. Barbero, F. Huegging et al. 'The shunt-LDO regulator to power the upgraded ATLAS pixel detector'. In: JINST 7 (2012), p. C01034. doi: 10.1088/1748-0221/7/01/C01034.
- M. Karagounis, Shunt-LDO RD53B features, talk, 2020 <u>https://indico.cern.ch/event/879686/contributions/3706455/attachments/1975390</u> /3287622/SLDO_RD53B_Features.pdf
- F. Winkler, Verification of Shunt-LDO, Master Thesis, 2019 <u>https://d-nb.info/1237320216/34</u>

Possible configuration for the ePIC SVT

 The ePIC SVT will be made of MAPS sensors consisting of single rows of (up to 9) stitched reticles, with the periphery at one end.



- Consider the substrate of the MAPS as the sensor and the reticules as the chips → an epic SVT MAPS sensor can be seen as an ATLAS ITk pixel module.
- Following the ATLAS scheme, for the ePIC SVT:
 - The current would flow in series between MAPS sensors.
 - Shunt-LDO regulators on the MAPS sensor will generate the required voltage(s) and regulate the current to the load.
- Note, direct powering is assumed for the vertex layers (for now).

Possible architecture for barrel layers

- The outermost sagitta layer, L4, is made of 1x7 sensors, it is two sensors wide and four sensor long (8 sensors per stave).
 - See baseline ePIC SVT configuration at <u>https://indico.bnl.gov/event/17713/</u>
- Top and side view of L4 (the stave is in grey).
 - Services would come in from the two sides.
 - The orientation of the periphery is to reduce the amount of services running on the stave.



- This simple configuration however leaves dead areas between sensors.
 - Periphery will need to be bonded to services flex/tape on stave, space not shown in this drawing.

Possible architecture for barrel layers

- · Sensors will most likely be needed on two sides to provide overlap.
 - This has an impact on the stave design, i.e. a truss structure would not be possible.



• In this configuration services could run as shown in blue.



 If now serial powering is added, this would mean four chains of two sensors per stave → the total current to L4 scales of a factor 2



Possible architecture for barrel layers

 Another possibility would be as shown below, giving a reduction factor 4 in the total current to L4



- For the innermost sagitta layer (L3), we would have chains of two sensors, giving a reduction factor 2 in the total current to L3
 - Made of 1x9 sensors, it is two sensors wide and two sensor long (4 sensors per stave).
 - Services come in from the side and connect to periphery at end of stave to minimise material.



• Note that most likely also in this case we might need sensors on two sides to avoid the gap in the middle.

Shunt-LDO: integrated or standalone

- This scheme implies the use of the Shunt-LDO, ideally integrated in the MAPS sensor.
- Implement Shunt-LDO in TJ 65 nm stand-alone block in ER2 to evaluate performance.
- Integrated version would need to wait first EIC LAS submission (currently scheduled tentatively for Q2-24).
- Backup option: standalone regulator.
 - Prototype Shunt-LDO design in TJ 180 nm MPW.
 - This would be positioned on the stave flex/tape, where the AC-coupling capacitors also are.

Next steps

- Reach out to RD53/Shunt-LDO designers to discuss regulator design (possibly IP sharing) and start design for submission with ER2 and standalone.
- Work on the current ideas to study engineering aspects of power and data distribution.
- Start exercise of evaluating material saving, to be refined as concept gets more detailed.
- Start thinking of conceptual design of SP scheme for disks.

What about DC-DC conversion?

 Some ideas were also discussed by Birmingham & RAL, will be presented another time.